CM200DU-34KA

HIGH POWER SWITCHING USE

CM200DU-34KA



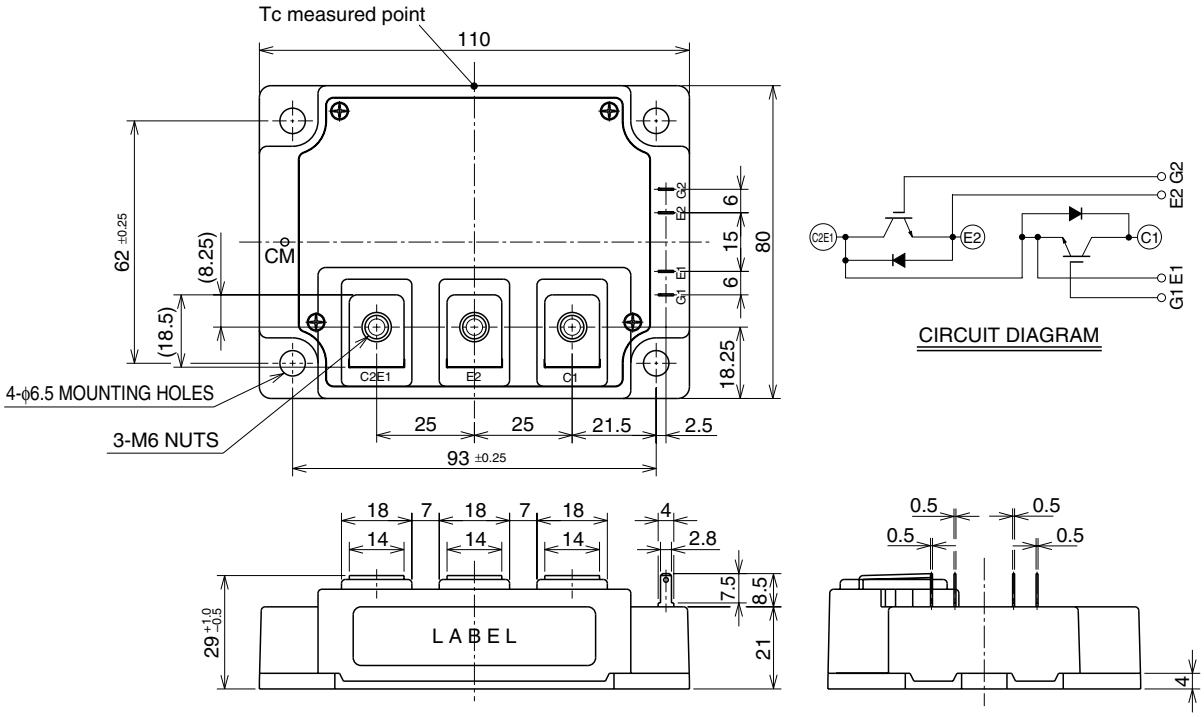
- I_C 200A
- V_{CES} 1700V
- Insulated Type
- 2-elements in a pack

APPLICATION

General purpose inverters & Servo controls, etc

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



CIRCUIT DIAGRAM

Sep. 2001

MITSUBISHI ELECTRIC

CM200DU-34KA

HIGH POWER SWITCHING USE

MAXIMUM RATINGS (Tj = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-emitter voltage	G-E Short	1700	V
V_{GES}	Gate-emitter voltage	C-E Short	±20	V
I_C	Collector current	T_C = 25°C	200	A
I_{CM}		Pulse (Note 2)	400	
I_E (Note 1)	Emitter current	T_C = 25°C	200	A
I_{EM} (Note 1)		Pulse (Note 2)	400	
P_C (Note 3)	Maximum collector dissipation	T_C = 25°C	1100	W
T_j	Junction temperature		–40 ~ +150	°C
T_{stg}	Storage temperature		–40 ~ +125	°C
V_{iso}	Isolation voltage	Main terminal to base plate, AC 1 min.	3500	V
—	Torque strength	Main Terminal M6	3.5 ~ 4.5	N • m
		Mounting holes M6	3.5 ~ 4.5	N • m
—	Weight	Typical value	580	g

ELECTRICAL CHARACTERISTICS (Tj = 25°C)

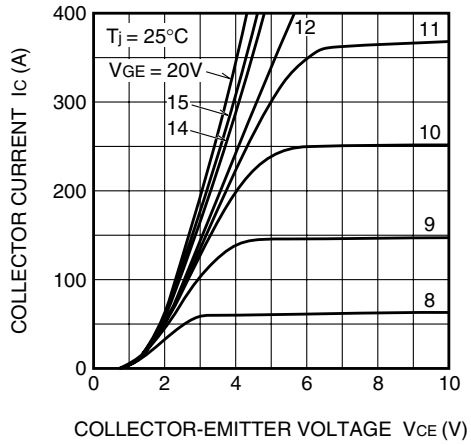
Symbol	Parameter	Test conditions		Limits			Unit
				Min.	Typ.	Max.	
I_{CES}	Collector cutoff current	V_{CE} = V_{CES}, V_{GE} = 0V		—	—	1	mA
$V_{GE(th)}$	Gate-emitter threshold voltage	I_C = 20mA, V_{CE} = 10V		4	5.5	7	V
I_{GES}	Gate leakage current	V_{GE} = V_{GES}, V_{CE} = 0V		—	—	0.5	µA
$V_{CE(sat)}$	Collector-emitter saturation voltage	T_j = 25°C	I_C = 200A, V_{GE} = 15V	—	3.2	4.0	V
		T_j = 125°C		—	3.8	—	
C_{ies}	Input capacitance	V_{CE} = 10V V_{GE} = 0V		—	—	29	nF
C_{oes}	Output capacitance			—	—	4.8	
C_{res}	Reverse transfer capacitance			—	—	1.5	
Q_G	Total gate charge	V_{CC} = 1000V, I_C = 200A, V_{GE} = 15V		—	900	—	nC
$t_{d(on)}$	Turn-on delay time	V_{CC} = 1000V, I_C = 200A V_{GE1} = V_{GE2} = 15V R_G = 1.6Ω, Inductive load switching operation I_E = 200A		—	—	600	ns
t_r	Turn-on rise time			—	—	200	
$t_{d(off)}$	Turn-off delay time			—	—	700	
t_f	Turn-off fall time			—	—	800	
t_{rr} (Note 1)	Reverse recovery time			—	—	600	ns
Q_{rr} (Note 1)	Reverse recovery charge			—	9.6	—	µC
V_{EC}(Note 1)	Emitter-collector voltage	I_E = 200A, V_{GE} = 0V, T_j = 25°C		—	—	4.6	V
		I_E = 200A, V_{GE} = 0V, T_j = 125°C		—	2.2	—	V
$R_{th(j-c)Q}$	Thermal resistance*1	IGBT part (1/2 module)		—	—	0.11	°C/W
$R_{th(j-c)R}$		FWDi part (1/2 module)		—	—	0.18	
$R_{th(c-f)}$	Contact thermal resistance	Case to fin, Thermal compound applied*2 (1/2 module)		—	0.02	—	
$R_{th(j-c')Q}$	Thermal resistance	Tc measured point is just under the chips		—	—	0.05*3	

Note 1. I_E, V_{EC}, t_{rr}, Q_{rr}, die/dt represent characteristics of the anti-parallel, emitter to collector free-wheel diode. (FWDi).
2. Pulse width and repetition rate should be such that the device junction temp. (T_j) does not exceed T_{jmax} rating.
3. Junction temperature (T_j) should not increase beyond 150°C.
4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

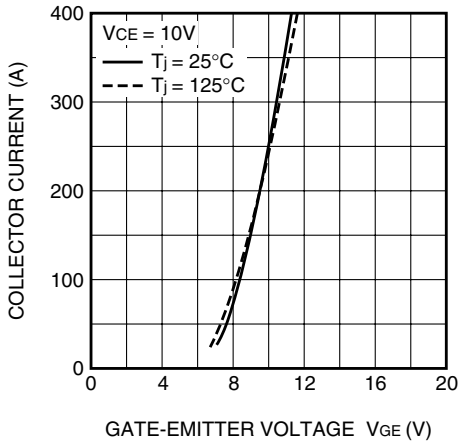
*1 : Tc measured point is indicated in OUTLINE DRAWING.
*2 : Typical value is measured by using Shin-etsu Silicone "G-746".
*3 : If you use this value, $R_{th(f-a)}$ should be measured just under the chips.

PERFORMANCE CURVES

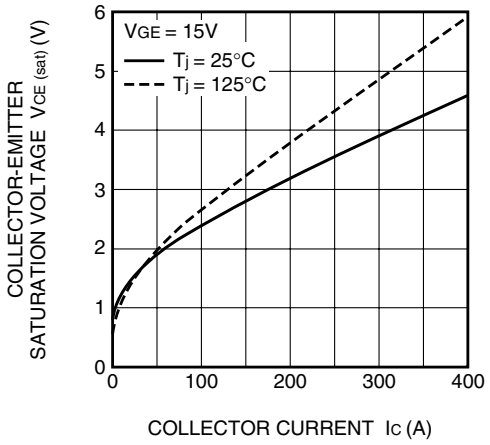
OUTPUT CHARACTERISTICS (TYPICAL)



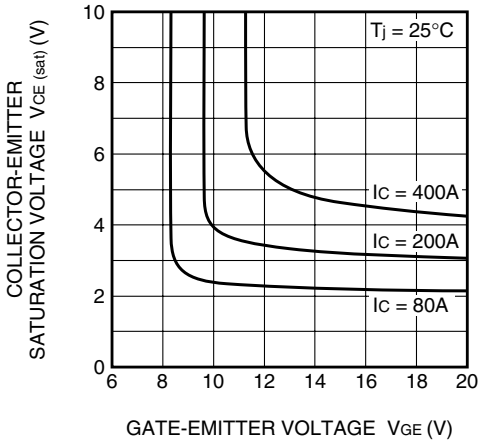
TRANSFER CHARACTERISTICS (TYPICAL)



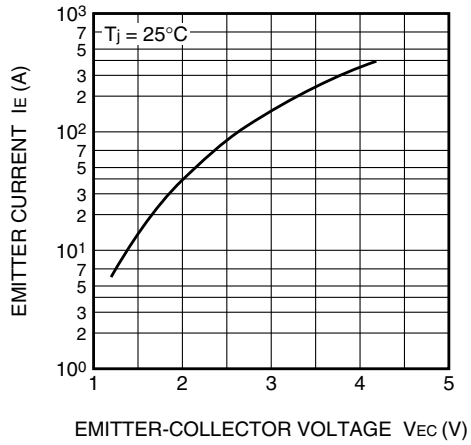
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



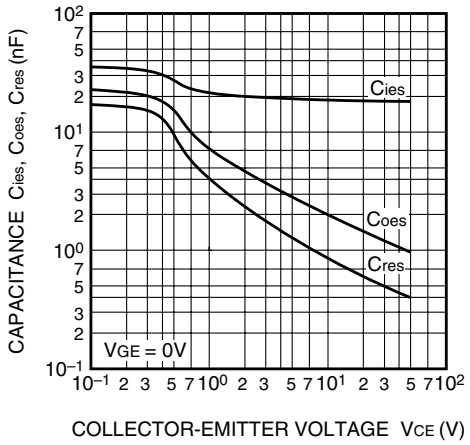
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



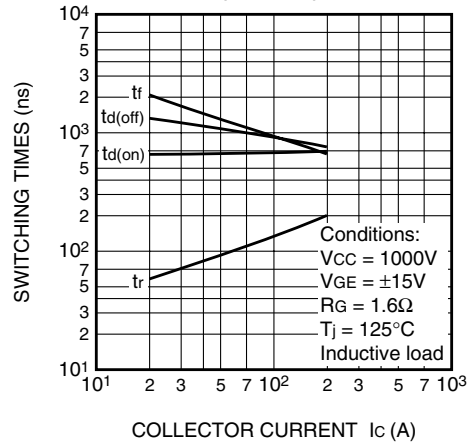
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



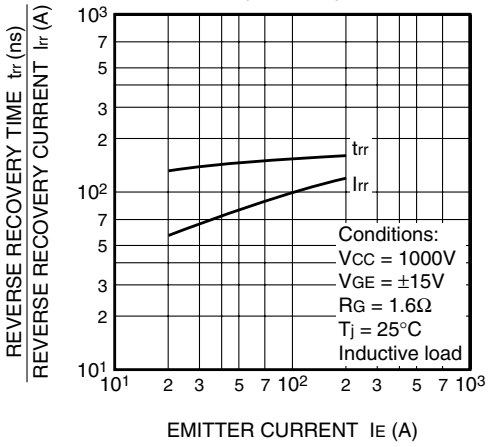
CAPACITANCE–VCE CHARACTERISTICS (TYPICAL)



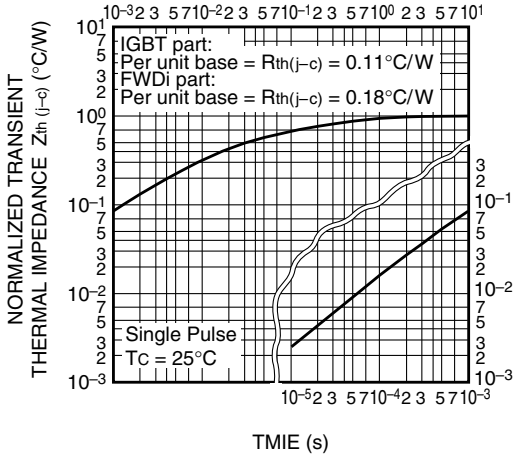
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



GATE CHARGE CHARACTERISTICS (TYPICAL)

